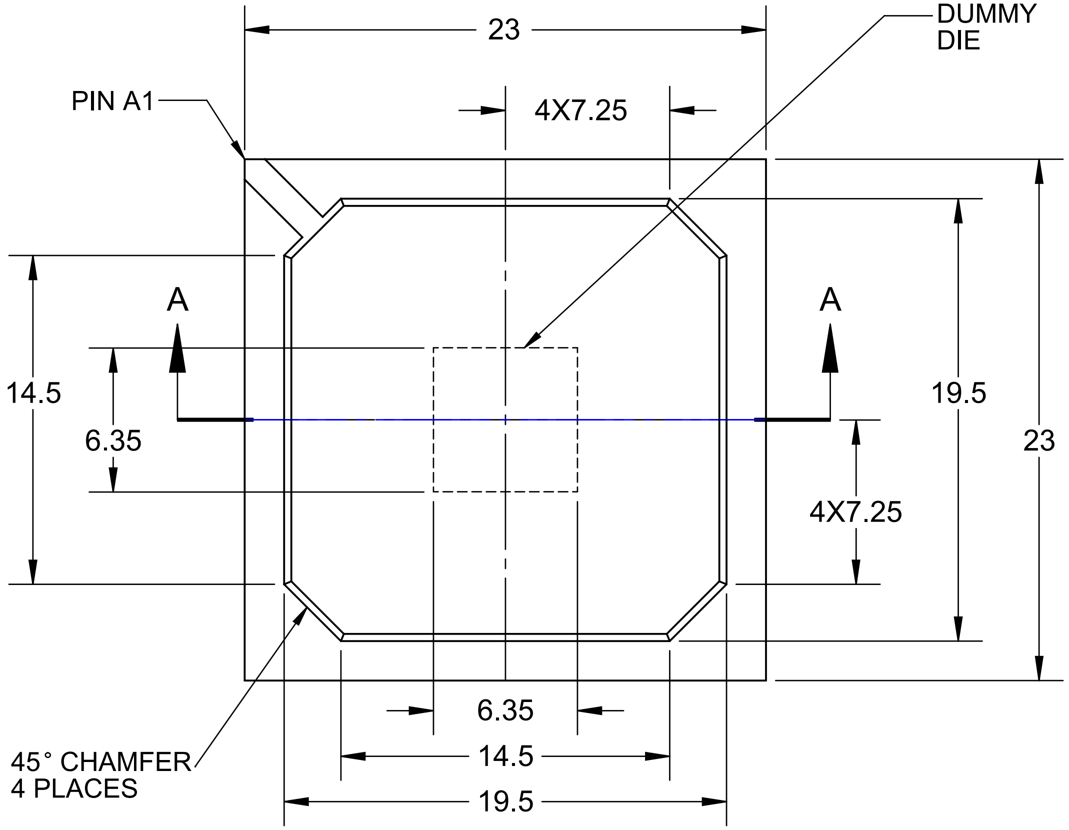
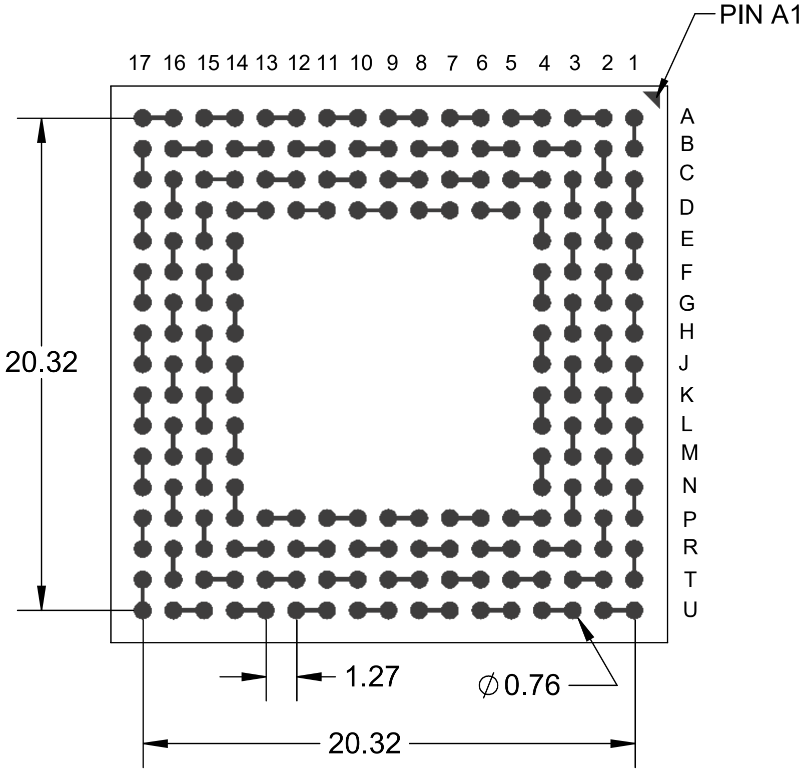
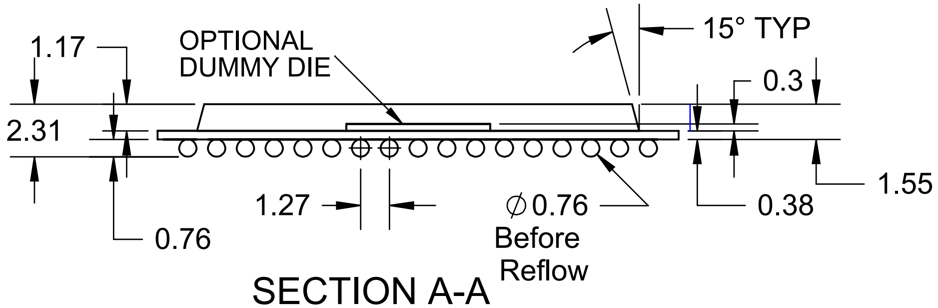
TOP VIEW



BALL VIEW





SECTION A-A

Notes: (Unless Otherwise Specified).

1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.76mm (30 MIL).
4) SOLDER MASK DEFINED PAD OPENING: 0.635mm (25 MIL).
5) PAD Cu DIAMETER: 0.762mm (30 MIL).
6) SUBSTRATE MATERIAL: BT.
7) DUMMY DIE IS OPTIONAL.
8) DAISY CHAIN PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA208T1.27C-DC170D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA208T1.27-DC170D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE
DRAWN	T.Au	6/23/2021
ENG	M. Hart	6/23/2021
MFG		
QA		
CUST		
REVISED		

TopLine®

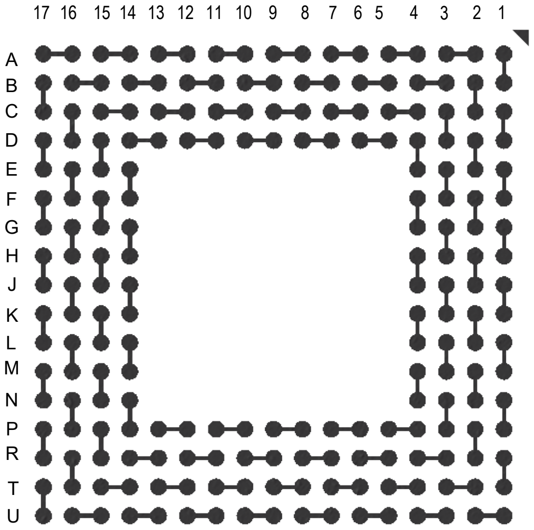
TITLE
BGA208T1.27-DC170D
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
3:1	A	521704	A

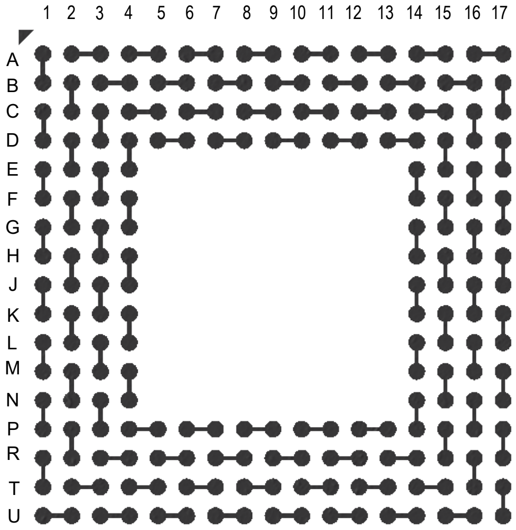
DO NOT SCALE DRAWING

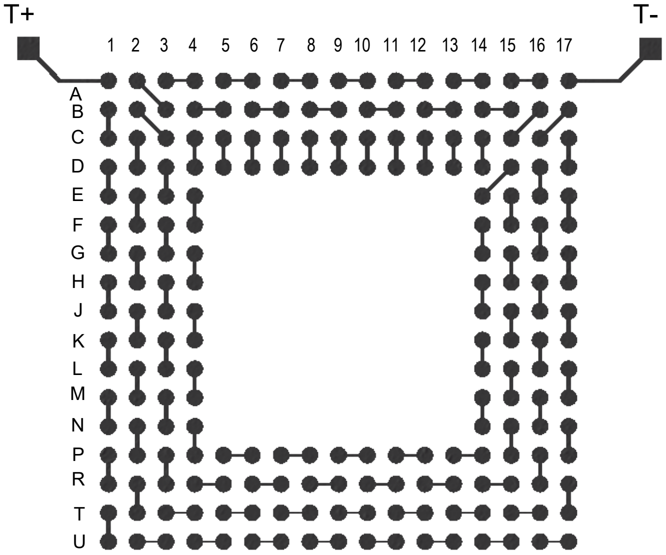
SHEET 1 OF 3

BALL VIEW

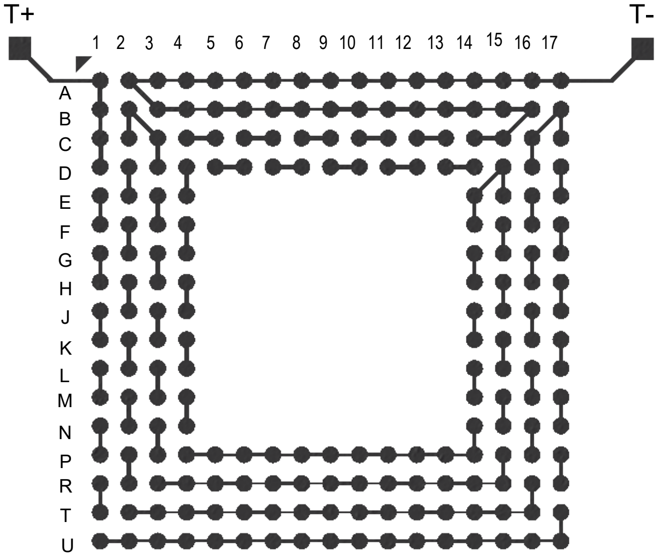


BOTTOM SIDE (TOP X-RAY VIEW)





TEST VEHICLE BOARD



AFTER MOUNT

Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER 0.762 (30 MIL).
3) PCB DAISY CHAIN TRACING LINE WIDTH 0.50 (20 MIL).
4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.635 (25 MIL).

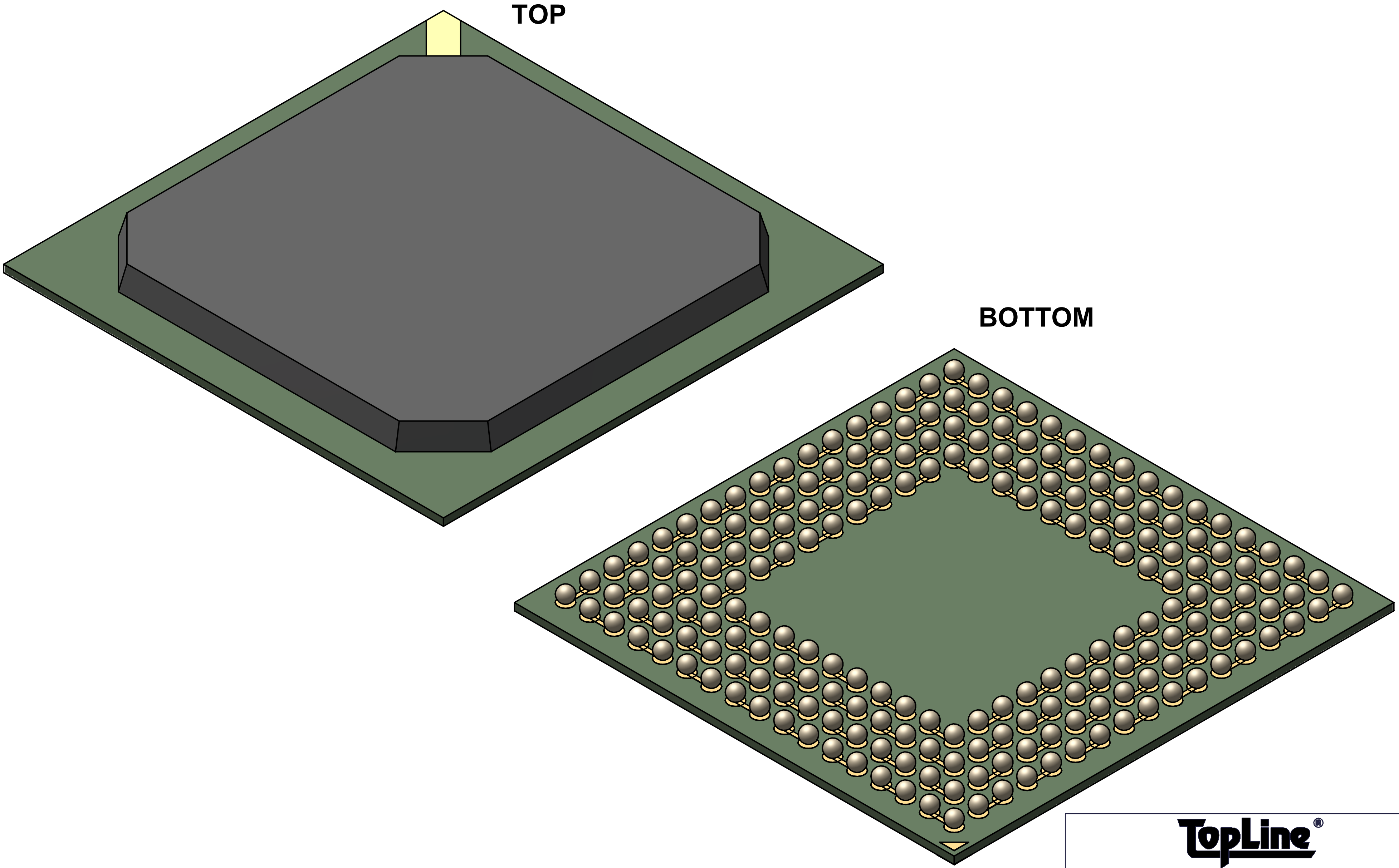
TopLine®

TITLE
BGA208T1.27-DC170D
DAISY CHAIN DUMMY

SCALE	SIZE	DRAWING NO.	REV
2.5:1	A	521704	A

DO NOT SCALE DRAWING
SHEET 2 OF 3

MODEL



TOP

BOTTOM

TopLine®

TITLE	BGA208T1.27-DC170D DAISY CHAIN DUMMY		
SCALE 2.5:1	SIZE A	DRAWING NO. 521704	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 3	